



ICC-279
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
Eadaoin Ledwidge) : Examiner: NYA
) : Group Art Unit: NYA
)
Application No.: 10/661,637 : Confirmation No.: NYA
)
Filed: September 15, 2003 :
)
For: CURABLE ENCAPSULANT :
COMPOSITIONS) September 29, 2003

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

Pursuant to 37 C.F.R. §§ 1.51(b), 1.56, 1.97 and 1.98, Applicant draws the Examiner's attention to the documents that appear listed on the attached Form PTO-1449. Copies of all such documents are attached hereto.

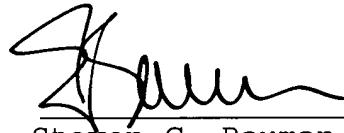
Applicant respectfully requests that each of these documents be considered by the Examiner, made of record herein, listed on the "Notice of References Cited" to be issued in this application and printed on any patent which may issue from this application. Applicant also respectfully requests that a copy of the attached Form PTO-1449, initialed by the Examiner, be returned to Applicant's attorney together with the next

communication indicating that these documents have in fact been considered.

Applicant requests a prompt and favorable examination of the instant application.

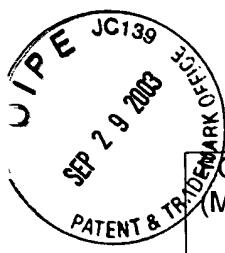
Applicant's undersigned attorney may be reached by telephone at (860) 520-5001 or by facsimile at (860) 543-7527. All correspondence should continue to be directed to the address given below.

Respectfully submitted,



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FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE (Modified) PATENT AND TRADEMARK OFFICE	ATTORNEY DOCKET NO.: ICC-279	APPLICATION NO.: 10/661,637
INFORMATION DISCLOSURE STATEMENT BY APPLICANT		
(Use Several Sheets if Necessary)		
<small>(37 CFR 1.98(b))</small>		

U.S. PATENT DOCUMENTS

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

Konarski, Mark M. and Heaton, Jim, Electronic Packaging Design Advances
Miniaturization, Circuits Assembly, pp. 32-35 (1996)

EXAMINER:	DATE CONSIDERED:
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